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APPLICATION NO.	FILING DATE	FIRST NAMED INVENTOR	ATTORNEY DOCKET NO.	CONFIRMATION NO.	
09/759,666	01/13/2001	Hiroaki Tsugane	15.29/5629	2708	
75	90 09/03/2002				
Konrad Rayness & Victor, LLP			EXAMINER		
315 South Beve Beverly Hills, C	rly Drive, Suite 210 CA 90212		SCHILLINGER	LLINGER, LAURA M	
			ART UNIT	PAPER NUMBER	
			2813	10	
			DATE MAILED: 09/03/2002	10	

Please find below and/or attached an Office communication concerning this application or proceeding.

		Application No.	Applicant(s)		
,		09/759,666	TSUGANE ET AL.		
• •	Office Action Summary	Examiner	Art Unit		
		Laura M Schillinger	2813		
Period fo	The MAILING DATE of this communication ap or Reply	ppears on the cover sheet wi	th the correspondence address		
THE - Exte after - If the - If NO - Failu - Any	ORTENED STATUTORY PERIOD FOR REP MAILING DATE OF THIS COMMUNICATION SIX (6) MONTHS from the mailing date of this communication. Experiod for reply specified above is less than thirty (30) days, a reduce to reply within the set or extended period for reply will, by stature to reply within the set or extended period for reply will, by stature ply received by the Office later than three months after the mailing adequates the mailing of the property of the mailing of the property of the mailing of th	136(a). In no event, however, may a reply within the statutory minimum of thirt will apply and will expire SIX (6) MON te, cause the application to become AB and date of this communication, even if the state of	eply be timely filed y (30) days will be considered timely. THS from the mailing date of this communication. ANDONED (35 U.S.C. § 133).		
2a)⊠					
3) Since this application is in condition for allowance except for formal matters, prosecution as to the merits is closed in accordance with the practice under <i>Ex parte Quayle</i> , 1935 C.D. 11, 453 O.G. 213.					
•	on of Claims				
	Claim(s) <u>1-8 and 15-23</u> is/are pending in the	•			
	4a) Of the above claim(s) is/are withdra	awn from consideration.			
	Claim(s) is/are allowed.				
	Claim(s) <u>1-8 and 15-23</u> is/are rejected.				
·	Claim(s) is/are objected to.				
=	Claim(s) are subject to restriction and/ on Papers	or election requirement.			
9)	The specification is objected to by the Examin	er.			
10)	The drawing(s) filed on is/are: a)□ acc	epted or b) objected to by the	ne Examiner.		
	Applicant may not request that any objection to t	he drawing(s) be held in abeya	ance. See 37 CFR 1.85(a).		
11) 🔲	The proposed drawing correction filed on	_ is: a)□ approved b)□ d	isapproved by the Examiner.		
	If approved, corrected drawings are required in re	eply to this Office action.			
12)	The oath or declaration is objected to by the E	xaminer.			
Priority (ınder 35 U.S.C. §§ 119 and 120				
13)	Acknowledgment is made of a claim for foreign	n priority under 35 U.S.C. §	§ 119(a)-(d) or (f).		
a)	☐ All b)☐ Some * c)☐ None of:				
	1. Certified copies of the priority documer	ts have been received.			
	2. Certified copies of the priority documer	ts have been received in A	pplication No		
* 5	3. Copies of the certified copies of the pricapplication from the International Bee the attached detailed Office action for a lis	ureau (PCT Rule 17.2(a)).	•		
14) 🗌 A	acknowledgment is made of a claim for domes	tic priority under 35 U.S.C.	§ 119(e) (to a provisional application).		
) The translation of the foreign language practice. Acknowledgment is made of a claim for domes	• •			
Attachmen	t(s)				
2) Notice 3) Inform	e of References Cited (PTO-892) e of Draftsperson's Patent Drawing Review (PTO-948) nation Disclosure Statement(s) (PTO-1449) Paper No(s)	5) Notice of I	Summary (PTO-413) Paper No(s) nformal Patent Application (PTO-152)		
.S. Patent and T PTO-326 (Re		Action Summary	Part of Paper No. 12		

' Art Unit: 2813

DETAILED ACTION

Claim Objections

Claim 16 is objected to because of the following informalities: misspelled conducting as "conducing"- appropriate correction is required). Appropriate correction is required.

Claim Rejections - 35 USC § 102

The following is a quotation of the appropriate paragraphs of 35 U.S.C. 102 that form the basis for the rejections under this section made in this Office action:

A person shall be entitled to a patent unless -

(e) the invention was described in a patent granted on an application for patent by another filed in the United States before the invention thereof by the applicant for patent, or on an international application by another who has fulfilled the requirements of paragraphs (1), (2), and (4) of section 371(c) of this title before the invention thereof by the applicant for patent.

Claims 1-8 and 15-18 are rejected under 35 U.S.C. 102(e) as being anticipated by Huckels et al('959).

In reference to claim 1, Huckels teaches a method comprising:

- a) simultaneously forming a storage node of the capacitor and lower electrode of the capacitor (Fig.1 (161) and Col.2, lines: 34-40);
- b) simultaneously forming a dielectric layer of the cell and element capacitor (Fig.1 (163) and Col.2, lines: 40-45);
- c) simultaneously forming a cell plate of the capacitor and upper electrode of the capacitor element (Fig.1 (165) and Col.2, lines: 35-40).

Art Unit: 2813

Response to Arguments

Applicant's arguments filed 6/11/02 have been fully considered but they are not persuasive. Applicant argues that that Huckels fails to describe a semiconductor device having a DRAM including a cell capacitor formed in a DRAM region of a substrate and a capacitor element formed in an analog element region of the semiconductor substrate, as recited in claim 1. This argument is not persuasive because the passage the applicant refers to is found within the preamble of the claim and is not patentable subject matter. The applicant failed to include a limitation for forming a DRAM within the limitation body of the claim, thus "referring back to" and thereby incorporating the language of the preamble into the body of the claim. Further, applicant should note that Col.2, Huckels teaches a DRAM cell with a trench capacitor. Consequently, the Examiner's rejection is deemed to be FINAL.

In reference to claim 2, Huckels teaches further comprising: forming a word line and a connection layer between the lower electrode and a separate element (Col.2, lines: 45-65).

In reference to claim 3, Huckels teaches further comprising forming a first resistance element and a second resistance element in the analog region by ion implantation(Col.3, lines: 64-68),

Wherein the first element is doped more than the second (Col.4, lines: 40-60).

In reference to claim 4, Huckels teaches further comprising forming a first resistance element and a second resistance element in the analog region by ion implantation(Col.3, lines: 64-68),

Art Unit: 2813

Wherein the first element is doped more than the second (Col.4, lines: 40-60).

In reference to claim 5, Huckels teaches further comprising forming a first resistance element and a second resistance element in the analog region by ion implantation (Col.3, lines: 64-68),

Wherein the first element has impurity diffusion thus doping more than the second (Col.4, lines: 15-30 and Col.4, lines: 40-60).) [applicant should note that dopants diffuse when exposed to heat- Huckels teaches that a large exposure to heat results in crystals formed from dopant diffusion- however dopants diffuse without the formation of crystals in smaller heat exposure doses -this is inherent in doped layers which are exposed to significant heat].

In reference to claim 6, Huckels teaches further comprising forming a first resistance element and a second resistance element in the analog region by ion implantation (Col.3, lines: 64-68),

Wherein the first element has impurity diffusion thus doping more than the second (Col.4, lines: 15-30 and Col.4, lines: 40-60).) [applicant should note that dopants diffuse when exposed to heat- Huckels teaches that a large exposure to heat results in crystals formed from dopant diffusion- however dopants diffuse without the formation of crystals in smaller heat exposure doses -this is inherent in doped layers which are exposed to significant heat]..

In reference to claim 7, Huckels teaches further comprising forming a first resistance element and a second resistance element in the analog region by ion implantation (Col.3, lines: 64-68),

Art Unit: 2813

Wherein the first element has a silicide layer thus less resistance than the second (Col.4, lines: 40-60 and Col.4, lines: 1-20).

In reference to claim 8, Huckels teaches further comprising forming a first resistance element and a second resistance element in the analog region by ion implantation (Col.3, lines: 64-68),

Wherein the first element has a silicide layer thus less resistance than the second (Col.4, lines: 40-60 and Col.4, lines: 1-20).

In reference to claim 15, Huckels teaches a method comprising:

- a) simultaneously forming a conductive storage node of the capacitor and a conductive lower electrode of the capacitor (Fig.1 (161) and Col.2, lines: 34-40);
- b) simultaneously forming a dielectric layer of the cell and element capacitor (Fig.1 (163) and Col.2, lines: 40-45);
- c) simultaneously forming a conductive cell plate of the capacitor and a conductive upper electrode of the capacitor element (Fig.1 (165) and Col.2, lines: 35-40).

Response to Arguments

Applicant's arguments filed 6/11/02 have been fully considered but they are not persuasive. Applicant argues that that Huckels fails to describe a semiconductor device having a DRAM including a cell capacitor formed in a DRAM region of a substrate and a capacitor element formed in an analog element region of the semiconductor substrate, as recited in claim 1. This argument is not persuasive because the passage the applicant refers to is found within the

Art Unit: 2813

preamble of the claim and is not patentable subject matter. The applicant failed to include a limitation for forming a DRAM within the limitation body of the claim, thus "referring back to" and thereby incorporating the language of the preamble into the body of the claim.

Consequently, the Examiner's rejection is deemed to be FINAL.

In reference to claim 16, Huckels teaches further comprising: forming a word line and a connection layer between the lower electrode and a separate element. (Col.2, lines: 45-65).

In reference to claim 17, Huckels teaches further comprising forming a first resistance element and a second resistance element in the analog region, wherein the first resistance is lower than the second (Col.4, lines: 40-60).

In reference to claim 18, Huckels teaches further comprising forming a first resistance element and a second resistance element in the analog region by ion implantation (Col.3, lines: 64-68), Wherein the first element is doped more than the second (Col.4, lines: 40-60).

In reference to claim 19, Huckels teaches wherein the etching a portion of the second conducting layer also forms a first resistance element and a second resistance element in the analog element region (Col.4, lines: 40-60).

Art Unit: 2813

In reference to claim 20, Huckels teaches further comprising performing at least one ion implantation of an impurity into part of the second conducting layer prior to the etching a portion of the second conducting layer (Col.3, lines: 64-68 and Fig.2A (215 and 230)).

In reference to claim 21, Huckels teaches wherein a number of ion implantations of impurity in a region where the first resistance element is to be formed is greater than a number of ionimplantations of impurity in a region where the second resistance element is tobe formed so that a resistance value of the first resistance element is lower than a resistance value of the second resistance element (Col.4, lines: 50-60).

In reference to claim 22, Huckels teaches wherein, prior to the etching a portion of the second conducting layer, an impurity is diffused in a region where the first resistance element is to be formed so that a resistance value of the first resistance element is lower than a resistance value of the second resistance element (Col.4, lines: 50-60).

In reference to claim 23, wherein prior to etching a portion of the second conducting layer, a silicide layer is formed in a region where the first resistance element is to be formed so that a resistance value of the first resistance element is lower than a resistance value of the second resistance element (Col.2, lines: 50-55).

Conclusion

Art Unit: 2813

THIS ACTION IS MADE FINAL. Applicant is reminded of the extension of time

Page 8

policy as set forth in 37 CFR 1.136(a).

A shortened statutory period for reply to this final action is set to expire THREE

MONTHS from the mailing date of this action. In the event a first reply is filed within TWO

MONTHS of the mailing date of this final action and the advisory action is not mailed until after

the end of the THREE-MONTH shortened statutory period, then the shortened statutory period

will expire on the date the advisory action is mailed, and any extension fee pursuant to 37

CFR 1.136(a) will be calculated from the mailing date of the advisory action. In no event,

however, will the statutory period for reply expire later than SIX MONTHS from the mailing

date of this final action.

Any inquiry concerning this communication or earlier communications from the

examiner should be directed to Laura M Schillinger whose telephone number is (703) 308-6425.

The examiner can normally be reached on M-F 7:00 -4:30.

If attempts to reach the examiner by telephone are unsuccessful, the examiner's

supervisor, Olik Chaudhuri can be reached on (703) 306-2794. The fax phone numbers for the

organization where this application or proceeding is assigned are (703) 308-7722 for regular

communications and (703) 308-7722 for After Final communications.

Any inquiry of a general nature or relating to the status of this application or proceeding

should be directed to the receptionist whose telephone number is (703) 308-1500.

C. Clarkary

LMS

August 28, 2002

Chandra Chaudhari

Primary Examiner